

Application No. 09/909,934
Filed: July 20, 2001
Group Art Unit: 2827

In the Specification

Please replace the first paragraph on p. 4, lines 1-12, with the following:

These and other objects of the present invention is—are accomplished by,

A stress-free lead frame (1) comprising;
~~a lead frame—(10)~~ having a plurality of integrated circuits areas (11), each of said plurality of integrated circuits areas having a die pad (12) and a plurality of leads (13); and
a peripheral pad (14) surrounding said ~~lead frame—(10)~~ plurality of integrated circuit areas,

characterized by

said peripheral pad (14) being provided with a plurality of stress-relief means (15).

Please replace the final paragraph beginning on p. 4, at line 24 and continuing to p. 5, line 9, with the following:

Referring now to FIG. 1 showing a lead frame of the prior art having a multiple integrated circuit units. A lead frame (2) of the prior art consists of a plurality of integrated circuits (20), each having a die pad (21) and a plurality of leads (22) projecting outwardly from the die pad (21). The integrated circuits (20) are connected together by connecting bars (23). At

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the outer periphery of the lead frame (2), there is an inactive portion of the lead frame (2) called the peripheral pad—(24) (not shown). When the lead frame (2) is moulded to form the MLP, about half of the peripheral pad—(24) is left unmoulded causing different expansions and thus delamination to the plurality of leads (22) adjacent to the peripheral pad—(24).

Please replace the second paragraph on p. 5, lines 10-19, with the following:

Referring to FIG. 2 showing a stress-free lead frame having a stress-relief means according to one embodiment of the present invention. The stress-free lead frame (1) comprises a lead frame (10) having a plurality of integrated circuit areas or integrated circuits (11) joined together by connecting bars (12). Each of the integrated circuits (11) ~~is having~~has a plurality of die pads (not shown) and leads (not shown) projecting outwardly from the die pads. A peripheral pad (14) surrounds the lead frame (10).

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In the Drawing:

Please replace sheets 1 and 2 (Figures 1 and 2) with replacement sheets 1 and 2 included herewith.

Figure 1 has been amended as follows:

1. The legend "Prior Art" has been added; and
2. Reference number 24 has been deleted.

Figure 2 has been amended as follows:

1. The numbers "4252A" and "5.739" at the bottom of the Figure have been deleted.